1 Features

- High Output Current: 250 mA
- Slew Rate: 2000 V/µs
- Pin-Selected Bandwidth: 30 MHz to 180 MHz
- Low Quiescent Current: 1.5 mA (30 MHz BW)
- Wide Supply Range: ±2.25 to ±18 V
- Internal Current Limit
- Thermal Shutdown Protection
- 8-Pin PDIP, SOIC-8, 5-Lead TO-220, 5-Lead DDPAK-TO-263 Surface-Mount

2 Applications

- Valve Driver
- Solenoid Driver
- Op Amp Current Booster
- Line Driver
- Headphone Driver
- Video Driver
- Motor Driver
- Test Equipment
- ATE Pin Driver

3 Description

The BUF634 device is a high speed, unity-gain open-loop buffer recommended for a wide range of applications. The BUF634 device can be used inside the feedback loop of op amps to increase output current, eliminate thermal feedback, and improve capacitive load drive.

For low power applications, the BUF634 device operates on 1.5-mA quiescent current with 250-mA output, 2000-V/µs slew rate, and 30-MHz bandwidth. Bandwidth can be adjusted from 30 MHz to 180 MHz by connecting a resistor between V– and the BW Pin.

Output circuitry is fully protected by internal current limit and thermal shut-down, making it rugged and easy to use.

The BUF634 device is available in a variety of packages to suit mechanical and power dissipation requirements. Types include 8-pin PDIP, SOIC-8 surface-mount, 5-lead TO-220, and a 5-lead DDPAK-TO-263 surface-mount plastic power package.

Device Information

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>BUF634</td>
<td>SOIC (8)</td>
<td>3.91 mm × 4.90 mm</td>
</tr>
<tr>
<td></td>
<td>PDIP (8)</td>
<td>6.35 mm × 9.81 mm</td>
</tr>
<tr>
<td></td>
<td>TO-220 (5)</td>
<td>8.51 mm × 10.16 mm</td>
</tr>
<tr>
<td></td>
<td>DDPAK/TO-263 (5)</td>
<td>8.42 mm × 10.16 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Boost the Output Current of any Operational Amplifier

![Circuit Diagram]
Table of Contents

1 Features ................................................................. 1
2 Applications ............................................................. 1
3 Description .............................................................. 1
4 Revision History ........................................................... 2
5 Pin Configuration and Functions ........................................... 3
6 Specifications ........................................................... 4
   6.1 Absolute Maximum Ratings ....................................... 4
   6.2 ESD Ratings .......................................................... 4
   6.3 Recommended Operating Conditions ......................... 4
   6.4 Thermal Information ............................................... 4
   6.5 Electrical Characteristics ....................................... 5
   6.6 Typical Characteristics .......................................... 6
7 Detailed Description .................................................. 10
   7.1 Overview ............................................................ 10
   7.2 Functional Block Diagram ....................................... 10
   7.3 Feature Description ............................................... 10
   7.4 Device Functional Modes ....................................... 11
8 Application and Implementation ....................................... 12
   8.1 Application Information ......................................... 12
   8.2 Typical Application .............................................. 13
9 Power Supply Recommendations ....................................... 15
10 Layout ................................................................. 15
   10.1 Layout Guidelines ............................................... 15
   10.2 Layout Example ................................................ 16
   10.3 Power Dissipation ................................................ 17
11 Device and Documentation Support .................................. 18
   11.1 Device Support .................................................. 18
   11.2 Documentation Support ...................................... 18
   11.3 Community Resource .......................................... 18
   11.4 Trademarks ...................................................... 18
   11.5 Electrostatic Discharge Caution ............................ 19
   11.6 Glossary ........................................................ 19
12 Mechanical, Packaging, and Orderable Information ......... 19

4 Revision History
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (September 2000) to Revision A

| Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. | 1 |

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.
## 5 Pin Configuration and Functions

### P and D Package
8-Pin PDIP and SOIC

- **BW**: Bandwidth adjust pin
- **NC**: No internal connection
- **V+**: Positive power supply
- **V-**: Negative power supply
- **VIN**: Input
- **VO**: Output

### KC Package
5-Pin TO-220

### KTT Package
5-Pin DDPAK/TO-263

### Pin Functions

<table>
<thead>
<tr>
<th>NAME</th>
<th>NO.</th>
<th>I/O</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>BW</td>
<td>1</td>
<td>I</td>
<td>Bandwidth adjust pin</td>
</tr>
<tr>
<td>NC</td>
<td>2, 5, 8</td>
<td>–</td>
<td>No internal connection</td>
</tr>
<tr>
<td>V+</td>
<td>7</td>
<td>I</td>
<td>Positive power supply</td>
</tr>
<tr>
<td>VIN</td>
<td>3</td>
<td>I</td>
<td>Input</td>
</tr>
<tr>
<td>VO</td>
<td>6</td>
<td>O</td>
<td>Output</td>
</tr>
<tr>
<td>V-</td>
<td>4</td>
<td>I</td>
<td>Negative power supply</td>
</tr>
</tbody>
</table>
# Specifications

## 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) \(^{(1)}\)

<table>
<thead>
<tr>
<th></th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply voltage</td>
<td>±18</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Input voltage</td>
<td>±(V_S)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Output short-circuit (to ground)</td>
<td>Continuous</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Operating temperature</td>
<td>–40</td>
<td>125</td>
<td>°C</td>
</tr>
<tr>
<td>Junction temperature</td>
<td>150</td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td>Lead temperature (soldering, 10 s)</td>
<td>300</td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature, (T_{stg})</td>
<td>–55</td>
<td>125</td>
<td>°C</td>
</tr>
</tbody>
</table>

\(^{(1)}\) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## 6.2 ESD Ratings

<table>
<thead>
<tr>
<th></th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>BUF634F in PDIP and SOIC Packages</td>
<td>(V_{\text{ESD}}) Electrostatic discharge Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (^{(1)})</td>
<td>±2500</td>
</tr>
<tr>
<td>BUF634F in SOIC-8 Package Only</td>
<td>(V_{\text{ESD}}) Electrostatic discharge, Charged-device model (CDM), per JEDEC specification JESD22-C101 (^{(2)})</td>
<td>±1000</td>
</tr>
<tr>
<td>BUF634F in TO-220 and DDPAK Packages</td>
<td>(V_{\text{ESD}}) Electrostatic discharge Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (^{(1)})</td>
<td>±2500</td>
</tr>
</tbody>
</table>

\(^{(1)}\) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

\(^{(2)}\) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

## 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

<table>
<thead>
<tr>
<th></th>
<th>MIN</th>
<th>NOM</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_s = (V+) - (V-)) Supply voltage</td>
<td>±2.25</td>
<td>±15</td>
<td>±18</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>(4.5)</td>
<td>(30)</td>
<td>(36)</td>
<td></td>
</tr>
<tr>
<td>(T_A) Operating temperature</td>
<td>–40</td>
<td>+25</td>
<td>+85</td>
<td>°C</td>
</tr>
</tbody>
</table>

## 6.4 Thermal Information

<table>
<thead>
<tr>
<th>THERMAL METRIC (^{(1)})</th>
<th>BUF634</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>PDIP</td>
</tr>
<tr>
<td></td>
<td>8 PINS</td>
</tr>
<tr>
<td>(R_{JA}) Junction-to-ambient thermal resistance</td>
<td>46.5</td>
</tr>
<tr>
<td>(R_{JC(top)}) Junction-to-case (top) thermal resistance</td>
<td>34.8</td>
</tr>
<tr>
<td>(R_{JB}) Junction-to-board thermal resistance</td>
<td>23.8</td>
</tr>
<tr>
<td>(\psi_{JT}) Junction-to-top characterization parameter</td>
<td>12</td>
</tr>
<tr>
<td>(\psi_{JB}) Junction-to-board characterization parameter</td>
<td>23.6</td>
</tr>
<tr>
<td>(R_{JC(bot)}) Junction-to-case (bottom) thermal resistance</td>
<td>n/a</td>
</tr>
</tbody>
</table>

\(^{(1)}\) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, *SPRA953*
6.5 Electrical Characteristics
At $T_A = +25^\circ C$ (1), $V_S = \pm 15 \, V$, specifications are for both low quiescent-current mode and wide-bandwidth mode unless otherwise specified.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Offset Voltage</td>
<td></td>
<td>±30</td>
<td>±100</td>
<td>mV</td>
<td></td>
</tr>
<tr>
<td>Offset Voltage vs Temperature</td>
<td>Specified Temperature Range</td>
<td>±100</td>
<td>µV/°C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Offset Voltage vs Power Supply</td>
<td>$V_S = \pm 2.25 , V$ to ±18 V</td>
<td>0.1</td>
<td>1</td>
<td>mV/V</td>
<td></td>
</tr>
<tr>
<td>Input Bias Current</td>
<td>$V_{IN} = 0V$</td>
<td>±0.5</td>
<td>±2</td>
<td>µA</td>
<td></td>
</tr>
<tr>
<td>Input Impedance</td>
<td>$R_L = 100 , \Omega$</td>
<td>80</td>
<td>8</td>
<td>MO</td>
<td>pF</td>
</tr>
<tr>
<td>Noise Voltage</td>
<td>$f = 10 , kHz$</td>
<td>0.95</td>
<td>0.99</td>
<td>V/V</td>
<td></td>
</tr>
<tr>
<td>Voltage Output</td>
<td></td>
<td>±250</td>
<td>mA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Positive I$_O$ = 10 mA</td>
<td>(V+) –2.1 (V+) –1.7</td>
<td></td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Negative I$_O$ = –10 mA</td>
<td>(V–) +2.1 (V–) +1.8</td>
<td></td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Positive I$_O$ = 100 mA</td>
<td>(V+) –3 (V+) –2.4</td>
<td></td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Negative I$_O$ = –100 mA</td>
<td>(V–) +4 (V–) +3.5</td>
<td></td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Positive I$_O$ = 150 mA</td>
<td>(V+) –4 (V+) –2.8</td>
<td></td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Negative I$_O$ = –150 mA</td>
<td>(V–) +5 (V–) +4</td>
<td></td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Short-Circuit Current</td>
<td>Low Quiescent Current Mode</td>
<td>±350</td>
<td>±550</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Wide Bandwidth Mode</td>
<td>±400</td>
<td>±550</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

| DYNAMIC RESPONSE                      |                                          |      |      |      |      |
| Bandwidth, –3dB                        | $R_L = 1 \, k \Omega$                    | 30   |      | MHz  |      |
|                                        | $R_L = 100 \, \Omega$                    | 180  |      |      |      |
| Slew Rate                              | 20 Vp-p, $R_L = 100 \, \Omega$          | 2000 |      | V/µs |      |
| Settling Time                          | 0.1% 20-V Step, $R_L = 100 \, \Omega$   | 200  |      | ns   |      |
|                                        | 1%                                         | 50   |      |      |      |
| Differential Gain                      | $3.58 \, MHz, V_O = 0.7 \, V$, $R_L = 150 \, \Omega$ | 4%   |      |      |      |
|                                        | Low Quiescent Current Mode               |      |      |      |      |
|                                        | Wide Bandwidth Mode                      | 0.4% |      |      |      |
| Differential Phase                     | $3.58 \, MHz, V_O = 0.7 \, V$, $R_L = 150 \, \Omega$ | 2.5  |      |      |      |
|                                        | Low Quiescent Current Mode               |      |      |      |      |
|                                        | Wide Bandwidth Mode                      | 0.1  |      |      |      |

| POWER SUPPLY                           |                                          |      |      |      |      |
| Specified Operating Voltage            |                                          | ±15  |      | V    |      |
| Operating Voltage Range               |                                          | ±2.25(2) | ±18 | V    |      |

(1) Tests are performed on high speed automatic test equipment, at approximately 25°C junction temperature. The power dissipation of this product will cause some parameters to shift when warmed up. See Typical Characteristics for over-temperature performance.
(2) Limited output swing available at low supply voltage. See Output voltage specifications.
Electrical Characteristics (continued)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{ V}$, specifications are for both low quiescent-current mode and wide-bandwidth mode unless otherwise specified.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_Q$ Quiescent Current</td>
<td>$I_Q = 0$</td>
<td>±1.5</td>
<td>±2</td>
<td>±15</td>
<td>mA</td>
</tr>
<tr>
<td></td>
<td>Low Quiescent</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Current Mode</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Wide Bandwidth</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**TEMPERATURE RANGE**

<table>
<thead>
<tr>
<th>Specification</th>
<th>$-40$</th>
<th>$85$</th>
<th>°C</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operating</td>
<td>$-40$</td>
<td>$125$</td>
<td>°C</td>
</tr>
<tr>
<td>$T_J$ Thermal Shutdown Temperature</td>
<td></td>
<td>$175$</td>
<td>°C</td>
</tr>
</tbody>
</table>

6.6 Typical Characteristics

At $T_A = 25^\circ\text{C}$, $V_S = \pm 15\text{ V}$, unless otherwise noted.

![Figure 1. Gain and Phase vs Frequency vs Quiescent Current](image1)

![Figure 2. Gain and Phase vs Frequency vs Temperature](image2)

![Figure 3. Gain and Phase vs Frequency vs Source Resistance](image3)

![Figure 4. Gain and Phase vs Frequency vs Load Resistance](image4)
Typical Characteristics (continued)

At $T_A = 25°C$, $V_S = ±15$ V, unless otherwise noted.

Figure 5. Gain and Phase vs Frequency vs Load Capacitance

Figure 6. Gain and Phase vs Frequency vs Load Capacitance

Figure 7. Gain and Phase vs Frequency vs Power Supply Voltage

Figure 8. Power Supply Rejection vs Frequency

Figure 9. Quiescent Current vs Bandwidth Control Resistance

Figure 10. Short-Circuit Current vs Temperature
Typical Characteristics (continued)

At $T_A = 25^\circ C$, $V_S = \pm 15$ V, unless otherwise noted.

Figure 11. Quiescent Current vs Temperature

Figure 12. Quiescent Current vs Temperature

Figure 13. Output Voltage Swing vs Output Current

Figure 14. Output Voltage Swing vs Output Current

Figure 15. Maximum Power Dissipation vs Temperature

Figure 16. Maximum Power Dissipation vs Temperature
**Typical Characteristics (continued)**

At $T_A = 25^\circ C$, $V_S = \pm 15$ V, unless otherwise noted.

<table>
<thead>
<tr>
<th>Wide BW Mode</th>
<th>Low $I_O$ Mode</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input</td>
<td>Input</td>
</tr>
<tr>
<td>100mV/div</td>
<td>100mV/div</td>
</tr>
<tr>
<td>20ns/div</td>
<td>20ns/div</td>
</tr>
</tbody>
</table>

**Figure 17. Small-Signal Response**  
$R_S = 50 \, \Omega, R_L = 100 \, \Omega$

**Figure 18. Large-Signal Response**  
$R_S = 50 \, \Omega, R_L = 100 \, \Omega$
7 Detailed Description

7.1 Overview

The BUF634 device is a high speed, unity-gain open-loop buffer recommended for a wide range of applications. The BUF634 device can be used inside the feedback loop of op amps to increase output current, eliminate thermal feedback, and improve capacitive load drive.

For low power applications, the BUF634 device operates on 1.5-mA quiescent current with 250-mA output, 2000-V/µs slew rate, and 30-MHz bandwidth. Bandwidth can be adjusted from 30 MHz to 180 MHz by connecting a resistor between V– and the BW Pin refer to Figure 9 and Figure 1. Output circuitry is fully protected by internal current limit and thermal shut-down, making it rugged and easy to use.

See the Functional Block Diagram section for a simplified circuit diagram of the BUF634 showing its open-loop complementary follower design.

7.2 Functional Block Diagram

7.3 Feature Description

7.3.1 Output Current

The BUF634 device can deliver up to ±250-mA continuous output current. Internal circuitry limits output current to approximately ±350 mA; see Figure 10. For many applications, however, the continuous output current will be limited by thermal effects.

The output voltage swing capability varies with junction temperature and output current (see Figure 14). Although all four package types are tested for the same output performance using a high speed test, the higher junction temperatures with the DIP and SO-8 package types often provide less output voltage swing. Junction temperature is reduced in the DDPAK surface-mount power package because it is soldered directly to the circuit board. The TO-220 package used with a good heat sink further reduces junction temperature, allowing maximum possible output swing.
7.4 Device Functional Modes

The BUF634 is operational when the power-supply voltage is greater than 4.5 V (±2.25 V). The maximum power supply voltage for the BUF634 is 36 V (±18 V). At low power supply conditions, such as ±2.25 V, the output swing may be limited. Refer to *Electrical Characteristics* for additional information.
8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

Figure 19 shows the BUF634 device connected as an open-loop buffer. The source impedance and optional input resistor, $R_S$, influence frequency response: see Typical Characteristics. Power supplies should be bypassed with capacitors connected close to the device pins. Capacitor values as low as 0.1 µF assure stable operation in most applications, but high output current and fast output slewing can demand large current transients from the power supplies. Solid tantalum 10-µF capacitors are recommended. High frequency open-loop applications may benefit from special bypassing and layout considerations. See High Frequency Applications for more information.

Figure 19. Buffer Connections

8.1.1 High Frequency Applications

The excellent bandwidth and fast slew rate of the BUF634 device are useful in a variety of high frequency open-loop applications. When operated open-loop, printed-circuit-board layout and bypassing technique can affect dynamic performance.

For best results, use a ground plane-type circuit board layout and bypass the power supplies with 0.1-µF ceramic chip capacitors at the device pins in parallel with solid tantalum 10-µF capacitors. Source resistance affects high-frequency peaking, step-response overshoot and ringing. Best response is usually achieved with a series input resistor of $25 \Omega$ to $200 \Omega$, depending on the signal source. Response with some loads (especially capacitive) can be improved with a resistor of $10 \Omega$ to $150 \Omega$ in series with the output.

Figure 20. High Performance Headphone Driver
Application Information (continued)

**Figure 21. Pseudo-Ground Driver**

**Figure 22. Current-Output Valve Driver**

**Figure 23. Bridge-Connected Motor Driver**

8.2 Typical Application

8.2.1 Boosting Op Amp Output Current

The BUF634 device can be connected inside the feedback loop of most op amps to increase output current (see Figure 24). When connected inside the feedback loop, the offset voltage of the BUF634 device and other errors are corrected by the feedback of the op amp.

**Figure 24. Boosting Op Amp Output Current**
Typical Application (continued)

8.2.1.1 Design Requirements
- Boost the output current of an OPA627
- Operate from ±15V power supplies
- Operate from -40°C to +85°C
- Gain = 23.5 V/V
- Output current = ±250 mA
- Bandwidth greater than 100 kHz

8.2.1.2 Detailed Design Procedure
To assure that the composite amplifier remains stable, the phase shift of the BUF634 device must remain small throughout the loop gain of the circuit. For a G=+1 op amp circuit, the BUF634 device must contribute little additional phase shift (approximately 20° or less) at the unity-gain frequency of the op amp. Phase shift is affected by various operating conditions that may affect stability of the op amp; see Typical Characteristics.

Most general-purpose or precision op amps remain unity-gain stable with the BUF634 device connected inside the feedback loop as shown. Large capacitive loads may require the BUF634 device to be connected for wide bandwidth for stable operation. High speed or fast-settling op amps generally require the wide bandwidth mode to remain stable and to assure good dynamic performance. To check for stability with an op amp, look for oscillations or excessive ringing on signal pulses with the intended load, and worst-case conditions that affect phase response of the buffer. Connect the circuit as shown in Figure 24. Choose resistors to provide a voltage gain of 23.5 V/V. Select the feedback resistor to be 2.7 kΩ. Choose the input resistor to be 120 Ω.

8.2.1.3 Application Curve

![Figure 25. Frequency Response of Composite Amplifier](image-url)
9 Power Supply Recommendations

The BUF634 is specified for operation from 4.5V to 36 V (±2.25 V to ±18 V). Many specifications apply from −40°C to +85°C. Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in the Typical Characteristics.

10 Layout

10.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit. Bypass capacitors are used to reduce the coupled noise by providing low-impedance power sources local to the analog circuitry.
  - Connect low-ESR, 0.1-µF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds paying attention to the flow of the ground current. For more detailed information refer to Circuit Board Layout Techniques, SLOA089.
- In order to reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If these traces cannot be kept separate, crossing the sensitive trace perpendicular is much better as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. As illustrated in Figure 27
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Cleaning the PCB following board assembly is recommended for best performance.
- Any precision integrated circuit may experience performance shifts due to moisture ingress into the plastic package. Following any aqueous PCB cleaning process, baking the PCB assembly is recommended to remove moisture introduced into the device packaging during the cleaning process. A low temperature, post cleaning bake at 85°C for 30 minutes is sufficient for most circumstances.

Power dissipated in the BUF634 device causes the junction temperature to rise. A thermal protection circuit in the BUF634 device disables the output when the junction temperature reaches approximately 175°C. When the thermal protection is activated, the output stage is disabled, allowing the device to cool. Quiescent current is approximately 6 mA during thermal shutdown. When the junction temperature cools to approximately 165°C, the output circuitry is again enabled. This can cause the protection circuit to cycle on and off with a period ranging from a fraction of a second to several minutes or more, depending on package type, signal, load and thermal environment.

The thermal protection circuit is designed to prevent damage during abnormal conditions. Any tendency to activate the thermal protection circuit during normal operation is a sign of an inadequate heat sink or excessive power dissipation for the package type.

The TO-220 package provides the best thermal performance. When the TO-220 is used with a properly sized heat sink, output is not limited by thermal performance. See Application Bulletin AB-037 for details on heat sink calculations. The DDPACK also has excellent thermal characteristics. Its mounting tab should be soldered to a circuit board copper area for good heat dissipation. Figure 26 shows typical thermal resistance from junction to ambient as a function of the copper area. The mounting tab of the TO-220 and DDPACK packages is electrically-connected to the V– power supply.

The DIP and SO-8 surface-mount packages are excellent for applications requiring high output current with low average power dissipation. To achieve the best possible thermal performance with the DIP or SO-8 packages, solder the device directly to a circuit board. Because much of the heat is dissipated by conduction through the package pins, sockets will degrade thermal performance. Use wide circuit board traces on all the device pins, including pins that are not connected. With the DIP package, use traces on both sides of the printed circuit board if possible.
Layout Guidelines (continued)

Figure 26. Thermal Resistance vs Circuit Board Copper Area

10.2 Layout Example

Figure 27. BUF634 Layout Example
10.1 Power Dissipation

Power dissipation depends on power supply voltage, signal, and load conditions. With DC signals, power dissipation is equal to the product of output current times the voltage across the conducting output transistor, $V_S - V_O$. Power dissipation can be minimized by using the lowest possible power supply voltage necessary to assure the required output voltage swing.

For resistive loads, the maximum power dissipation occurs at a DC output voltage of one-half the power supply voltage. Dissipation with AC signals is lower. Application Bulletin SBOS022 explains how to calculate or measure power dissipation with unusual signals and loads.

Any tendency to activate the thermal protection circuit indicates excessive power dissipation or an inadequate heat sink. For reliable operation, junction temperature should be limited to 150°C, maximum. To estimate the margin of safety in a complete design, increase the ambient temperature until the thermal protection is triggered. The thermal protection should trigger more than 45°C above the maximum expected ambient condition of your application.
11 Device and Documentation Support

11.1 Device Support

11.1.1 TINA-TI™ (Free Software Download)

TINA™ is a simple, powerful, and easy-to-use circuit simulation program based on a SPICE engine. TINA-TI is a free, fully-functional version of the TINA software, preloaded with a library of macro models in addition to a range of both passive and active models. TINA-TI provides all the conventional dc, transient, and frequency domain analysis of SPICE, as well as additional design capabilities.

Available as a free download from the Analog eLab Design Center, TINA-TI offers extensive post-processing capability that allows users to format results in a variety of ways. Virtual instruments offer the ability to select input waveforms and probe circuit nodes, voltages, and waveforms, creating a dynamic quick-start tool.

NOTE
These files require that either the TINA software (from DesignSoft™) or TINA-TI software be installed. Download the free TINA-TI software from the TINA-TI folder.

11.1.2 TI Precision Designs

The BUF634 is featured in several TI Precision Designs, available online at http://www.ti.com/. TI Precision Designs are analog solutions created by TI's precision analog applications experts and offer the theory of operation, component selection, simulation, complete PCB schematic and layout, bill of materials, and measured performance of many useful circuits.

11.2 Documentation Support

11.2.1 Related Documentation

For related documentation, please see the following:

- Circuit Board Layout Techniques, SLOA089.
- Combining an Amplifier with the BUF634, SBOA065
- Add Current Limit to the BUF634, SBOA042
- Power Amplifier Stress and Power Handling Limitations, SBOA022
- Shelf-Life Evaluation of Lead-Free Component Finishes, SZZA046

11.3 Community Resource

The following links connect TI community resources. Linked contents are provided “AS IS” by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI’s views; see TI’s Terms of Use.

- TI E2E™ Online Community TI’s Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.
- Design Support TI’s Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

TINA-TI is a trademark of Texas Instruments, Inc and DesignSoft, Inc.
TINA, DesignSoft are trademarks of DesignSoft, Inc.
All other trademarks are the property of their respective owners.
11.5 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
## PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>PINS</th>
<th>Package Qty</th>
<th>Eco Plan</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
<th>Device Marking</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>BUF634F/500</td>
<td>ACTIVE</td>
<td>DDPAK/TO-263</td>
<td>KTT</td>
<td>5</td>
<td>500</td>
<td>Pb-Free (RoHS)</td>
<td>CU SN</td>
<td>Level-2-260C-1 YEAR</td>
<td>-40 to 125</td>
<td>BUF634F</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634F/500E3</td>
<td>ACTIVE</td>
<td>DDPAK/TO-263</td>
<td>KTT</td>
<td>5</td>
<td>500</td>
<td>Pb-Free (RoHS)</td>
<td>CU SN</td>
<td>Level-2-260C-1 YEAR</td>
<td>-40 to 125</td>
<td>BUF634F</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634FKTTT</td>
<td>ACTIVE</td>
<td>DDPAK/TO-263</td>
<td>KTT</td>
<td>5</td>
<td>250</td>
<td>Pb-Free (RoHS)</td>
<td>CU SN</td>
<td>Level-2-260C-1 YEAR</td>
<td>-40 to 125</td>
<td>BUF634F</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634FKTTTE3</td>
<td>ACTIVE</td>
<td>DDPAK/TO-263</td>
<td>KTT</td>
<td>5</td>
<td>250</td>
<td>Pb-Free (RoHS)</td>
<td>CU SN</td>
<td>Level-2-260C-1 YEAR</td>
<td>-40 to 125</td>
<td>BUF634F</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634P</td>
<td>ACTIVE</td>
<td>PDIP</td>
<td>P</td>
<td>8</td>
<td>50</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>N / A for Pkg Type</td>
<td>-40 to 125</td>
<td>BUF634P</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634PG4</td>
<td>ACTIVE</td>
<td>PDIP</td>
<td>P</td>
<td>8</td>
<td>50</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>N / A for Pkg Type</td>
<td>-40 to 125</td>
<td>BUF634P</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634T</td>
<td>ACTIVE</td>
<td>TO-220</td>
<td>KC</td>
<td>5</td>
<td>49</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU SN</td>
<td>N / A for Pkg Type</td>
<td>-40 to 125</td>
<td>BUF634T</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634TG3</td>
<td>ACTIVE</td>
<td>TO-220</td>
<td>KC</td>
<td>5</td>
<td>49</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU SN</td>
<td>N / A for Pkg Type</td>
<td>-40 to 125</td>
<td>BUF634T</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634U</td>
<td>ACTIVE</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>75</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>Level-3-260C-168 HR</td>
<td>-40 to 125</td>
<td>BUF634U</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634U/2K5</td>
<td>ACTIVE</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>Level-3-260C-168 HR</td>
<td>-40 to 125</td>
<td>BUF634U</td>
<td>Samples</td>
</tr>
<tr>
<td>BUF634UE4</td>
<td>ACTIVE</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>75</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>Level-3-260C-168 HR</td>
<td>-40 to 125</td>
<td>BUF634U</td>
<td>Samples</td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:
- **ACTIVE**: Product device recommended for new designs.
- **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.
- **OBSOLETE**: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check [http://www.ti.com/productcontent](http://www.ti.com/productcontent) for the latest availability information and additional product content details.
- **TBD**: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS)**: TI’s terms “Lead-Free” or “Pb-Free” mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.
## TAPE AND REEL INFORMATION

### TAPE DIMENSIONS

<table>
<thead>
<tr>
<th><strong>Device</strong></th>
<th><strong>Package Type</strong></th>
<th><strong>Package Drawing</strong></th>
<th><strong>Pins</strong></th>
<th><strong>SPQ</strong></th>
<th><strong>Reel Diameter (mm)</strong></th>
<th><strong>Reel Width W1 (mm)</strong></th>
<th><strong>A0 (mm)</strong></th>
<th><strong>A0 (mm)</strong></th>
<th><strong>K0 (mm)</strong></th>
<th><strong>P1 (mm)</strong></th>
<th><strong>W (mm)</strong></th>
<th><strong>Pin1 Quadrant</strong></th>
</tr>
</thead>
<tbody>
<tr>
<td>BUF634F/500</td>
<td>DDPAK/T0-263</td>
<td>KTT</td>
<td>5</td>
<td>500</td>
<td>330.0</td>
<td>24.4</td>
<td>10.6</td>
<td>15.6</td>
<td>4.9</td>
<td>16.0</td>
<td>24.0</td>
<td>Q2</td>
</tr>
<tr>
<td>BUF634FKTTT</td>
<td>DDPAK/T0-263</td>
<td>KTT</td>
<td>5</td>
<td>250</td>
<td>330.0</td>
<td>24.4</td>
<td>10.6</td>
<td>15.6</td>
<td>4.9</td>
<td>16.0</td>
<td>24.0</td>
<td>Q2</td>
</tr>
<tr>
<td>BUF634U/2K5</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>330.0</td>
<td>12.4</td>
<td>6.4</td>
<td>5.2</td>
<td>2.1</td>
<td>8.0</td>
<td>12.0</td>
<td>Q1</td>
</tr>
</tbody>
</table>

*All dimensions are nominal.*

- **A0**: Dimension designed to accommodate the component width
- **B0**: Dimension designed to accommodate the component length
- **K0**: Dimension designed to accommodate the component thickness
- **W**: Overall width of the carrier tape
- **P1**: Pitch between successive cavity centers
TAPE AND REEL BOX DIMENSIONS

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Length (mm)</th>
<th>Width (mm)</th>
<th>Height (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>BUF634F/500</td>
<td>DDPACK/TO-263</td>
<td>KTT</td>
<td>5</td>
<td>500</td>
<td>367.0</td>
<td>367.0</td>
<td>45.0</td>
</tr>
<tr>
<td>BUF634FKTTT</td>
<td>DDPACK/TO-263</td>
<td>KTT</td>
<td>5</td>
<td>250</td>
<td>367.0</td>
<td>367.0</td>
<td>45.0</td>
</tr>
<tr>
<td>BUF634U2K5</td>
<td>SOIC</td>
<td>D</td>
<td>8</td>
<td>2500</td>
<td>367.0</td>
<td>367.0</td>
<td>35.0</td>
</tr>
</tbody>
</table>

*All dimensions are nominal
NOTES:

A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

⚠️ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0.15) each side.

⚠️ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0.43) each side.
E. Reference JEDEC MS-012 variation AA.
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC-7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Shape may vary per different assembly sites.
NOTES:  
A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. Falls within JEDEC MS-001 variation BA.
MECHANICAL DATA

KTT (R-PSFM-G5) PLASTIC FLANGE-MOUNT PACKAGE

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
   Falls within JEDEC TO-263 variation BA, except minimum lead thickness, maximum seating height, and minimum body length.

4200577-4/G 01/13
NOTES:

A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC—SM—782 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release.
   Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.

TEXAS INSTRUMENTS
www.ti.com
Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. TI’s published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, “Designers”) understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers’ applications and compliance of their applications (and of all TI products used in or for Designers’ applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI’s provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, “TI Resources”) are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer’s company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI’s provision of TI Resources does not expand or otherwise alter TI’s applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY PATENT, COPYRIGHT, MASK WORK, SEMICONDUCTOR DESIGN OR ANY OTHER INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED “AS IS” AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE, IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers’ own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer’s non-compliance with the terms and provisions of this Notice.